

**Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V <sub>RM</sub>	100	V
Peak Repetitive Reverse Voltage	V <sub>RPM</sub>	80	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Blocking Voltage	V <sub>R</sub>		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	57	V
Forward Continuous Current (Note 5)	I <sub>FM</sub>	500	mA
Average Rectified Output Current (Note 5)	I <sub>O</sub>	250	mA
Non-Repetitive Peak Forward Surge Current	I <sub>FSM</sub>	4.0	A
		1.0	
		@ t = 1.0μs	
		@ t = 1.0s	

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>D</sub>	350	mW
Thermal Resistance Junction to Ambient Air (Note 5)	R <sub>θJA</sub>	357	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

**Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V <sub>(BR)R</sub>	80	—	V	I <sub>R</sub> = 2.5μA
Forward Voltage	V <sub>F</sub>	0.62	0.72	V	I <sub>F</sub> = 5.0mA
		—	0.855		I <sub>F</sub> = 10mA
		—	1.0		I <sub>F</sub> = 100mA
		—	1.25		I <sub>F</sub> = 150mA
Reverse Current (Note 6)	I <sub>R</sub>	—	100	nA	V <sub>R</sub> = 70V
			50	μA	V <sub>R</sub> = 75V, T <sub>J</sub> = 150°C
			30	μA	V <sub>R</sub> = 25V, T <sub>J</sub> = 150°C
			25	nA	V <sub>R</sub> = 20V
Total Capacitance	C <sub>T</sub>	—	3.5	pF	V <sub>R</sub> = 6, f = 1.0MHz
Reverse Recovery Time	t <sub>rr</sub>	—	4.0	ns	V <sub>R</sub> = 6V, I <sub>F</sub> = 5mA

Notes: 5. Device mounted on FR-5 PCB 1.0 x 0.75 x 0.062 inch pad layout as shown on Diodes Inc. suggested pad layout AP02001, which can be found on our website at <http://www.diodes.com>.  
 6. Short duration pulse test used to minimize self-heating effect.

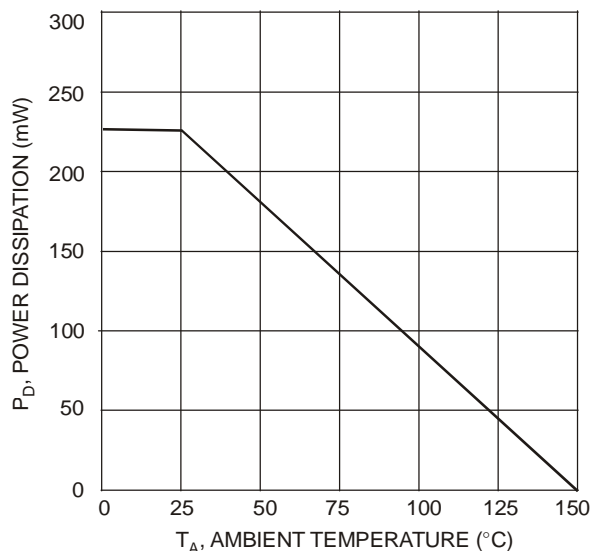


Fig. 1 Power Derating Curve, Total Package (Note 5)

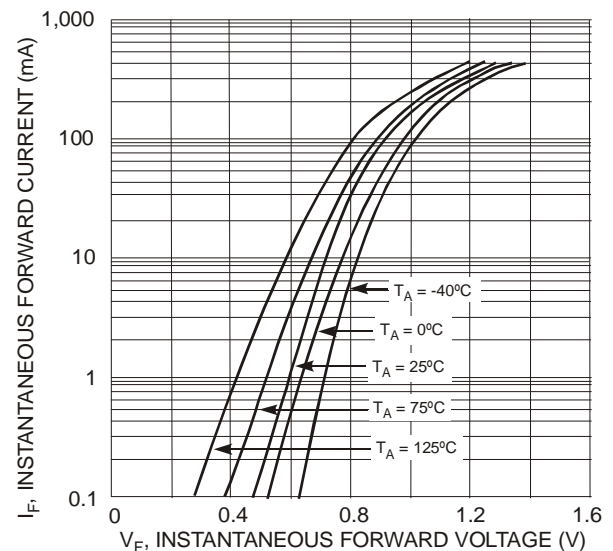


Fig. 2 Typical Forward Characteristics, Per Element

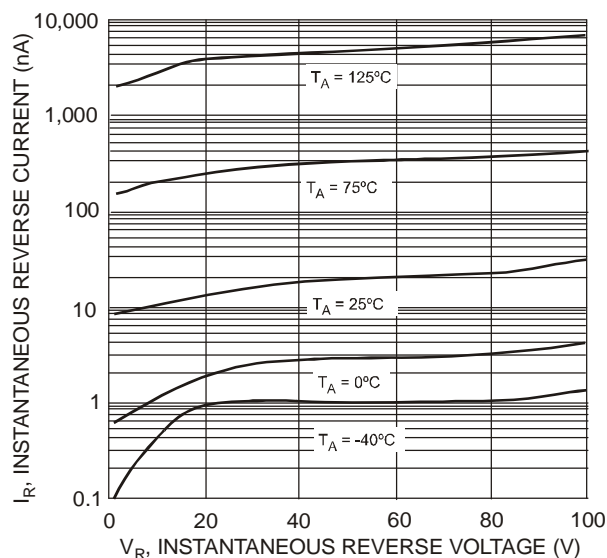


Fig. 3 Typical Reverse Characteristics, Per Element

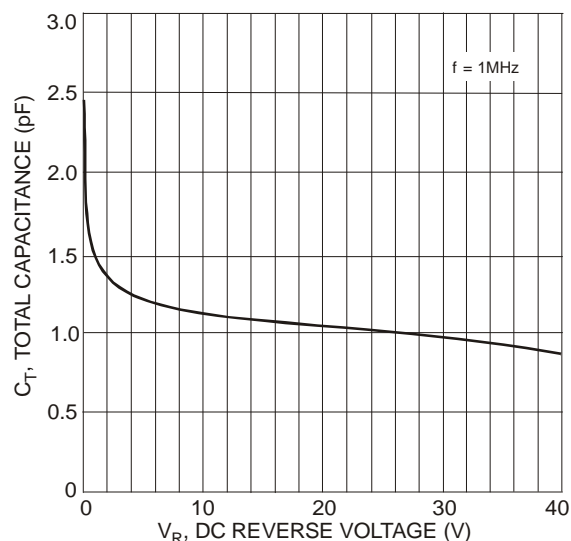
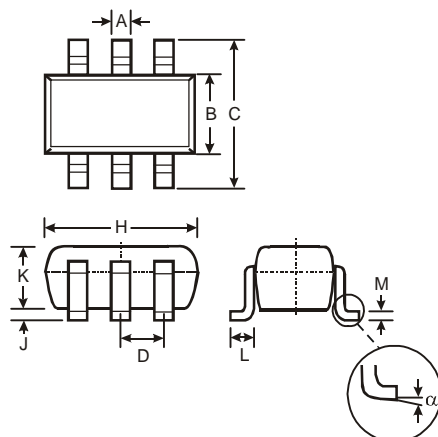


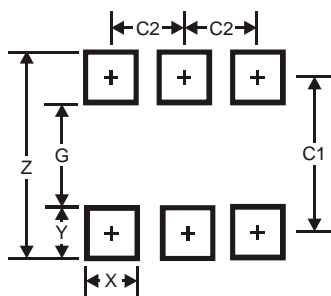
Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

## Package Outline Dimensions



SOT-26			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	—	—	0.95
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
α	0°	8°	—
All Dimensions in mm			

## Suggested Pad Layout



Dimensions	Value (in mm)
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95

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